US-HS-207
High Strength, High Temperature Silicone Adhesive Sealant

US-HS-207 is a high strength, high temperature silicone RTV engineered for applications requiring fast development of physical properties and excellent adhesion. This offers the highest temperature resistance of any acetoxy cure silicone currently available. When cured, the elastomers resist weathering, ozone, moisture, UV and high temperatures. Works well in manual and automatic dispensing equipment.

Product Features
- Fast Room Temperature cure
- Instant Cure Capability
- Thixotropic paste
- Convenient, Heat Accelerated
- Excellent unprimed adhesion to plastic, metal and glass

Typical Applications
- Assembly line adhesive
- Adhesive Sealant
- Form in place gaskets

Heat Accelerated Curing

Typical utilization involves dispensing in open air and ambient humidity to result in a high strength adhesive rubber. However, cure speed can be accelerated with hot air to nearly instant cures exhibiting very fast adhesion. A one minute hot air stream exposure, followed by a one minute cool down in a humid environment, results in cured elastomer condition exhibiting outstanding adhesion.

Method of Application
Dispense dressing onto gasket and flange surface. Install component and tighten fasteners to the manufacturer’s torque specifications, thus sealing all surface irregularities with the fastener clamping force.

Chemical cure system: Acetoxy cure system

Typical Properties

Uncured:
- Color: Translucent Red
- Viscosity, cps: 500,000
- Specific Gravity: 1.14
- Consistency Working time, mins: 4
- Tack Free Time, mins.: 12
- Application Rate, 90 PSI, g/min: 250, 3mm orifice at 0.6 MPa

Cured - Room Temperature:
- Max. Operating Temp: 330°C
- Physical Properties:
  - Tensile Strength, PSI: 1000
  - Peel Strength, PPI: 50
  - Dielectric Strength, V/mil >500
  - Volume Resistivity: 2.0 X 1014
  - Thermal conductivity: 0.0005
  - Elongation, %: 850
  - Dielectric Constant: 2.8
  - Dissipation Factor: 0.001
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HEAT AGED 24 Hours at 330°C
- Durometer Elongation
  - Tensile: 772 (-22.8%)
  - Elongation: 850% (0)

Method of Application:
Dispense sealant onto part and mate parts. Do not squeeze all of the product out of flange assembly. Allow to cure.

Chemical cure system: Acetoxy cure system

Solids:
- 98% solids, contains no solvents

Adhesion:
- Primerless adhesion to most plastics, metals and typical substrates.

Limitations:
- Do not use product on head gaskets, fuel or solvent immersion applications. Allow sealant to fully cure before putting assembly into service. Ensure enough product remains between flanges to be effective in an assembly.

Packaging:
- Available in, 10.3 oz. cartridges, 40 lb. pails and 400 lb. drums. This product is also available in customer defined packaging sizes, upon request.

Handling and safety:
- For maximum shelf life, keep containers sealed when not in use. Keep out of the reach of children. Uncured sealant irritates eyes and skin. Refer to MSDS.

Shelf-life:
- Sealed containers guaranteed for 1 year from the ship date when stored in a cool dry area below 70°F.

Applicable standards:
- Conforms to MIL-A-46106B Type I Group III